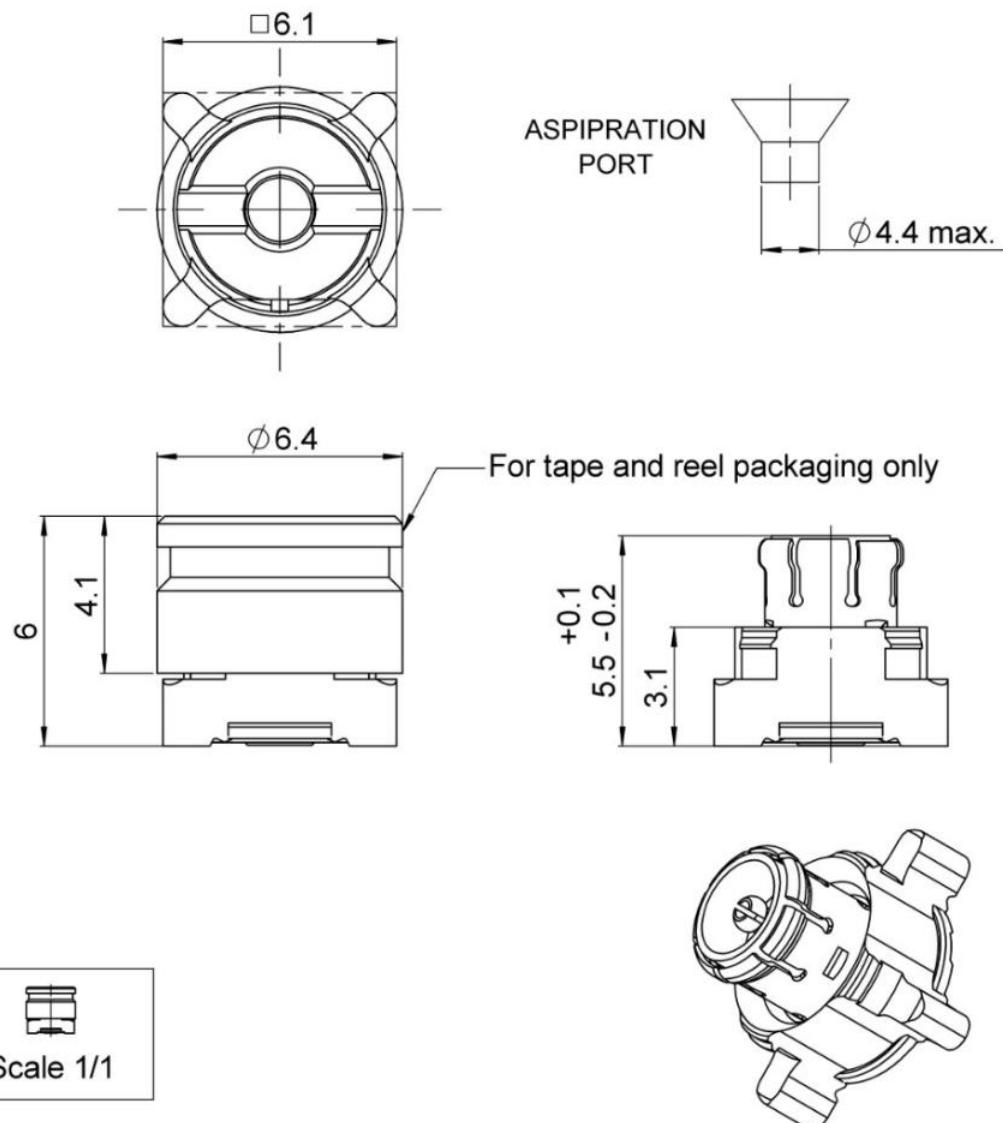


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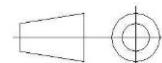
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SERIES MMBX

PART NUMBER R223434926



All dimensions are in mm. Tolerances according ISO 2768 m-H



COMPONENTS	MATERIALS	PLATING (μm)
Body	BERYLLIUM COPPER; BRASS	BBR OVER SILVER
Center contact	BERYLLIUM COPPER; BRASS	Silver
Outer contact		
Insulator	LCP	
Gasket	PTFE	
Others parts		
-	-	-
-	-	-

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SERIES MMBX

PART NUMBER R223434926

PACKAGING

Standard	Unit	Other
750	Contact us	Contact us

ELECTRICAL CHARACTERISTICS

Impedance	50	Ω
Frequency	0-12.4	GHz
VSWR	*1.065	+ 0 x F(GHz) Maxi
Insertion loss	0.12	$\sqrt{F(GHz)}$ dB Maxi
RF leakage	**100	- F(GHz) dB Maxi
Voltage rating	330	Veff Maxi
Dielectric withstanding voltage	1000	Veff mini
Insulation resistance	1000	MΩ mini

ENVIRONMENTAL

Operating temperature	-55/+155	°C
Hermetic seal	NA	Atm.cm ³ /s
Panel leakage	NA	

MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating End	NA	N mini
Axial force – Opposite end	NA	N mini
Torque	NA	N.cm mini
Recommended torque		
Mating	NA	N.cm
Panel nut	NA	N.cm
Mating life	100	Cycles mini
Nominal Weight (Add +15% for max weight)	0,58	g

SPECIFICATION

OTHER CHARACTERISTICS

Assembly instruction:**NA**

Others:

* Up to 2GHz ; 1.106max @ 2-6 GHz

**Interface only,up to 2.5 GHz

PIM3<= -140dBc,2x30dBm @700,900,1800,2600MHz

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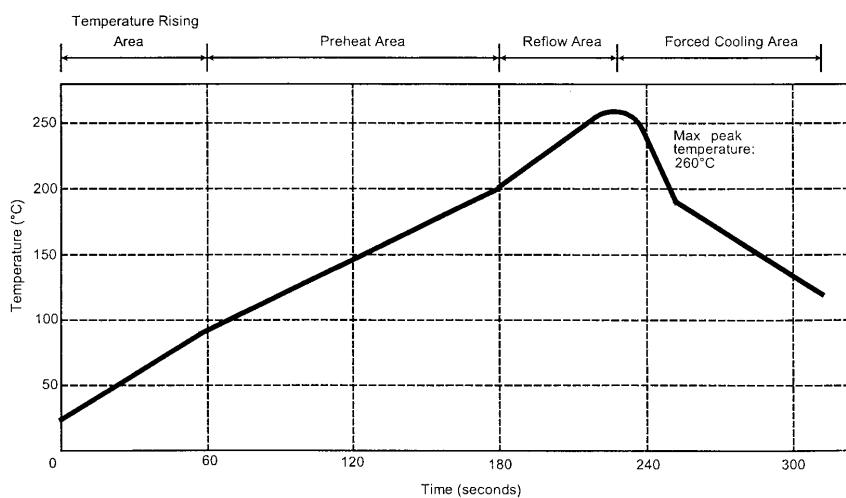
SERIES MMBX

PART NUMBER R223434926

SOLDER PROCEDURE

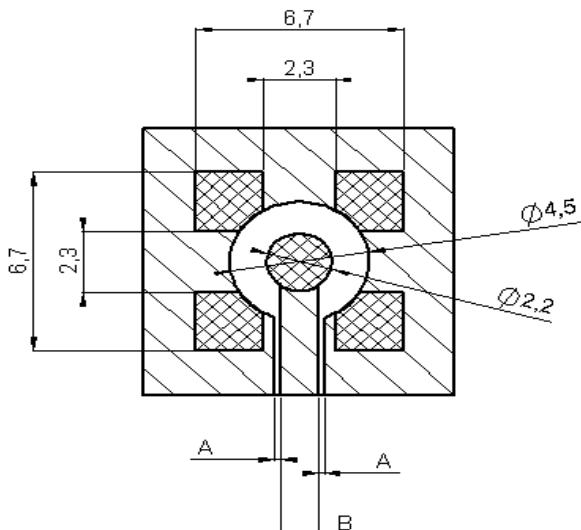
1. Deposit solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux. We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. A video camera is recommended for positioning of the component. Adhesive agents must not be used on the receptacle.
3. This process of soldering has been tested with convection oven .Below please find, the typical profile to use.
4. The cleaning of printed circuit boards is not obliged.
5. Verification of solder joints and position of the component by visual inspection

TEMPERATURE PROFILE



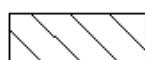
Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

PCB



COPLANAR LINE

Pattern and signal are on the same side
The material of PCB is epoxy resin (FR4).
($\epsilon_r = 4.6$)
The solder resist should be printed
Except for the land pattern on the PCB



Pattern



Land for solder paste

APPLICATION 75Ω

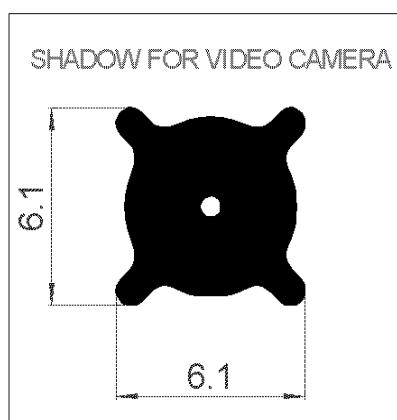
WITH B = 0.55mm

PCB thickness (mm)	Coplanar ligne A (mm)
0,8	0,350
1,0	0,360
1,2	0,365
1,6	0,375

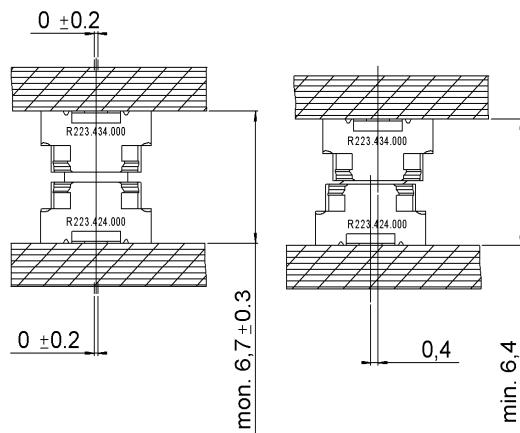
APPLICATION 50Ω

WITH B = 1.2mm

PCB thickness (mm)	Coplanar ligne A (mm)
0,8	0,190
1,0	0,200
1,2	0,205
1,6	0,210

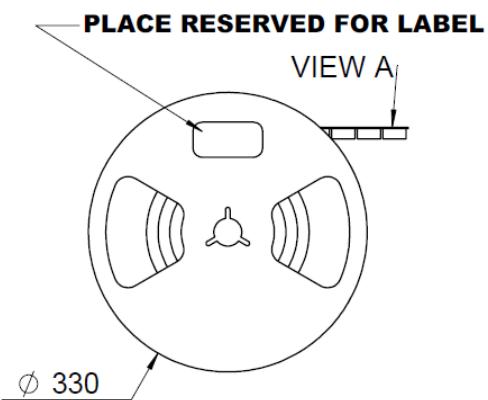


SET INFORAMTIONS



Only for set illustration.

PACKAGE



View A